# DATA SHEET



# PHOTOCOUPLER PS8741

# FOR OPTICAL DAA, HIGH LINEAR 16-PIN SOP PHOTOCOUPLER

-NEPOC Series-

#### **DESCRIPTION**

The PS8741 is an optically coupled isolator containing a GaAs LED on the input side and two photodiodes on the output side.

It is suitable for analog control applications such as PCMCIA card, modem, voice telephony and fax machines.

#### **FEATURES**

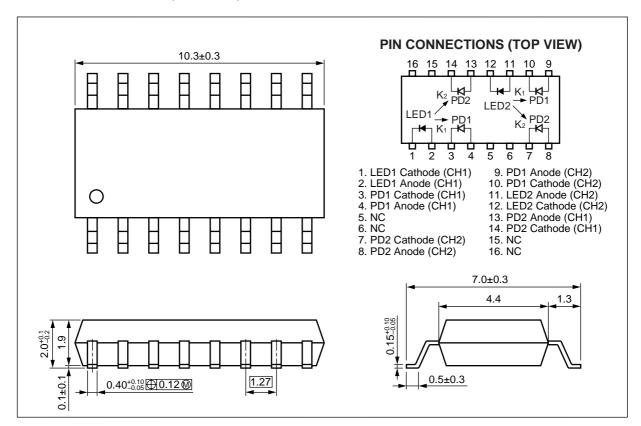
- For PCMCIA
- Small and thin package (16-pin SOP: Pin pitch = 1.27 mm, Height = 2.1 mm)
- High transfer gain linearity (∆K<sub>3</sub> = 1% MAX.)
- High isolation voltage (BV = 1 500 Vr.m.s.)
- Ordering number of taping product: PS8741-F3, F4: 2 500 pcs/reel
- · Safety standards
  - UL approved: File No. E72422 (S)

#### **APPLICATIONS**

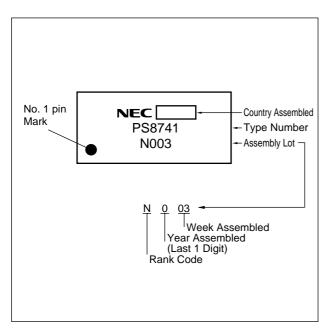
- PCMCIA card
- Notebook PC, PDA
- Modem
- · Telephone, FAX

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#### PACKAGE DIMENSIONS (UNIT: mm)



#### **MARKING**





#### **ORDERING INFORMATION**

Part Number	Package	Packing Style	Application Part Number*1
PS8741	16-pin SOP	Magazine case 45 pcs	PS8741
PS8741-F3		Embossed Tape 2 500 pcs/reel	
PS8741-F4			

<sup>\*1</sup> For the application of the Safety Standard, following part number should be used.

# ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

	Parameter	Symbol	Ratings	Unit
Diode	Forward Current (DC)	lF	50	mA
	Reverse Voltage	VR	3	V
	Power Dissipation	Po	80	mW/ch
	Peak Forward Current 1	IFP	0.5	Α
Detector	Reverse Voltage	VR	20	V
	Power Dissipation	Pc	50	mW/ch
Isolation	Voltage <sup>*²</sup>	BV	1 500	Vr.m.s.
Total Power Dissipation		Рт	180	mW
Operating Ambient Temperature		TA	-40 to +85	°C
Storage Temperature		T <sub>stg</sub>	-40 to +100	°C

<sup>\*1</sup> PW = 100  $\mu$ s, Duty Cycle = 1%

# **ELECTRICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)**

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	I <sub>F</sub> = 5 mA		1.1	1.4	V
	Reverse Current	lr	VR = 3 V			10	μΑ
	Terminal Capacitance	Ct	V = 0 V, f = 1 MHz		30		pF
Detector	Dark Current	ΙD	Vcc = 5 V, I <sub>F</sub> = 0 mA		1	25	nA
Coupled	Servo Gain (IPD1/IF)	<b>K</b> 1	Vcc = 5 V, I <sub>F</sub> = 2 mA	0.3	1.0	1.8	%
	Forward Gain (IPD2/IF)	K <sub>2</sub>		0.3	1.0	1.8	
	Transfer Gain (K <sub>2</sub> /K <sub>1</sub> )	Kз	Vcc = 5 V, I <sub>F</sub> = 2 mA	0.75	1.0	1.25	
	Transfer Gain Linearity	∆K₃	Vcc = 5 V, I <sub>F</sub> = 2 to 10 mA		0.3	1	%
	K <sub>3</sub> Temperature Coefficient	ΔK3/ΔT	$V_{CC} = 5 \text{ V}, \text{ IF} = 2 \text{ to } 10 \text{ mA},$ $T_{A} = -40 \text{ to } +85^{\circ}\text{C}$		0.005		%/°C

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<sup>\*2</sup> AC voltage for 1 minute at  $T_A = 25$ °C, RH = 60% between input and output

#### **★ USAGE CAUTIONS**

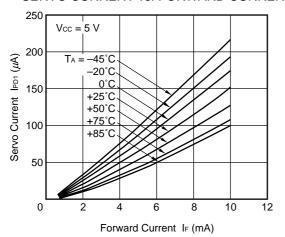
1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.

- 2. By-pass capacitor of more than 0.1  $\mu$ F is used between Vcc and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
- 3. Avoid storage at a high temperature and high humidity.

# **NEC**

#### TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

#### SERVO CURRENT vs. FORWARD CURRENT



#### SERVO GAIN vs. FORWARD CURRENT

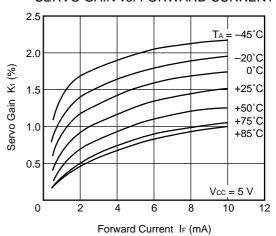
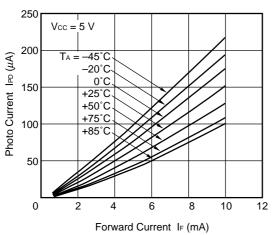
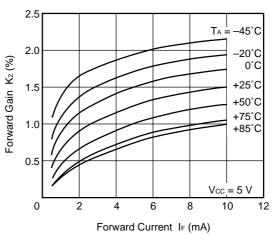


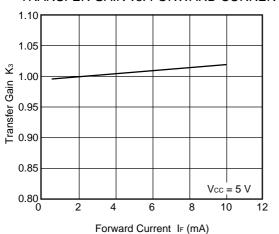
PHOTO CURRENT vs. FORWARD CURRENT



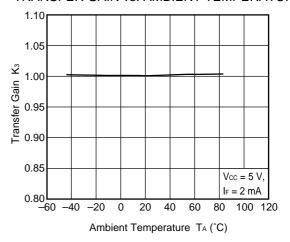
FORWARD GAIN vs. FORWARD CURRENT



TRANSFER GAIN vs. FORWARD CURRENT

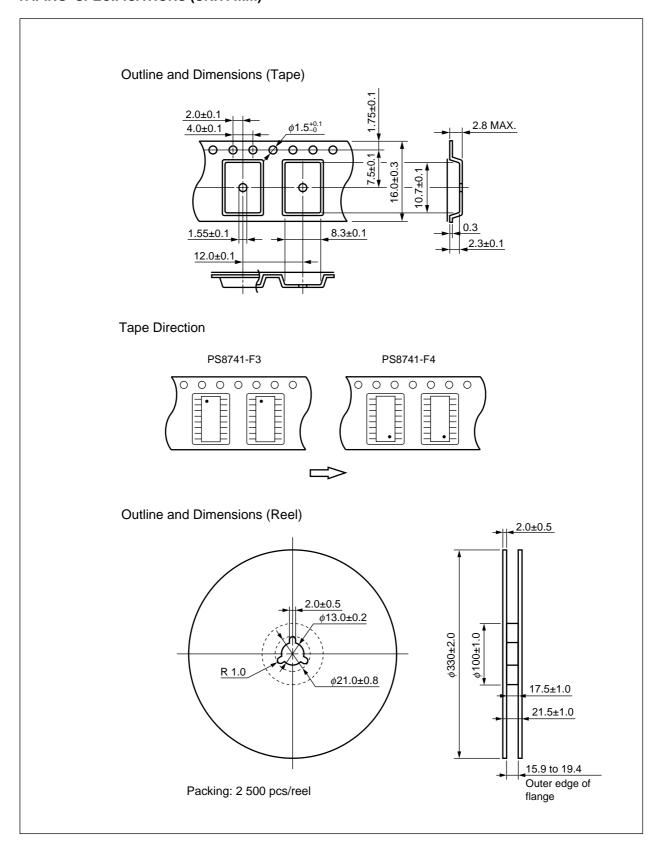


TRANSFER GAIN vs. AMBIENT TEMPERATURE



Remark The graphs indicate nominal characteristics.

# TAPING SPECIFICATIONS (UNIT: mm)





#### RECOMMENDED SOLDERING CONDITIONS

### (1) Handling (Soldering iron)

Temperature 260°C or belowTime 5 seconds or less

• Leave more than 1.0 mm from the lead roof

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt % is recommended.)

(2) Infrared reflow soldering

• Peak reflow temperature 235°C (Package surface temperature)

• Time of temperature higher than 210°C 30 seconds or less

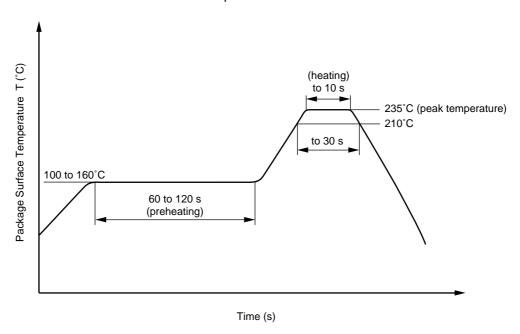
Preheating conditions
 100 to 160°C (Package surface temperature), 60 to 120 seconds

• Number of reflows One

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt % is recommended.)

#### Recommended Temperature Profile of Infrared Reflow



# (3) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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#### SAFETY INFORMATION ON THIS PRODUCT

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GaAs Products

The product contains gallium arsenide, GaAs.

GaAs vapor and powder are hazardous to human health if inhaled or ingested.

- Do not destroy or burn the product.
- Do not cut or cleave off any part of the product.
- Do not crush or chemically dissolve the product.
- Do not put the product in the mouth.

Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

#### ▶For further information, please contact

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